

Major Ratings and Characteristics

$I_{F(AV)}$	2.0 A
V_{RRM}	20 V to 100 V
I_{FSM}	40 A
V_F	0.50V , 0.55 V , 0.70 V , 0.85V
$T_j \text{ max.}$	125 °C

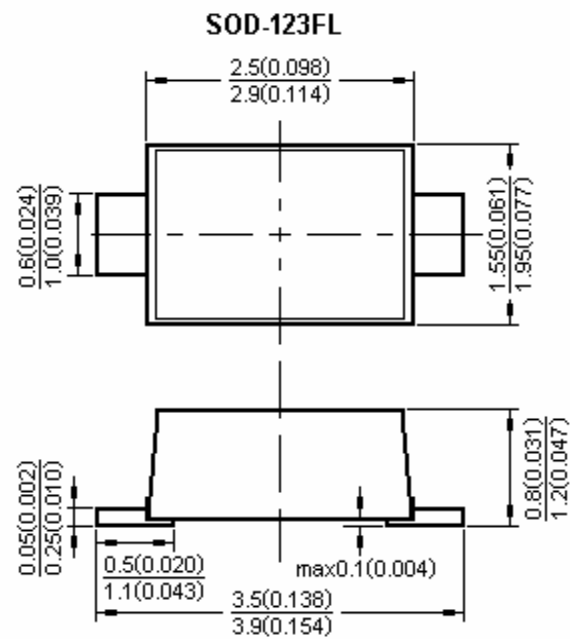


Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Date

- **Case:** JEDEC SOD-123FL molded plastic body over passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end
- **Weight:** 0.017gram



Dimensions in millimeters and (inches)

Maximum Ratings & Thermal Characteristics & Electrical Characteristics

($T_A = 25\text{ °C}$ unless otherwise noted)

	Symbol	DSK22	DSK23	DSK24	DSK25	DSK26	DSK28	DSK210	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	V
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	V
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	V
Maximum average forward rectified current	$I_{F(AV)}$	2							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	40							A
Maximum instantaneous forward voltage at 2.0A	V_F	0.50	0.55	0.70		0.85		V	
Maximum DC reverse current at Rated DC blocking voltage	I_R	1.0 10							mA
Typical thermal resistance	$R_{\theta JL}$	28							°C/W
Operating junction and storage temperature range	T_J, T_{STG}	- 65 to +125							°C

Note1: Mounted on FR-4 P.C.B. With 0.9x1.5 mm copper pad areas ($\approx 35\text{ }\mu\text{m}$ thick)



Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

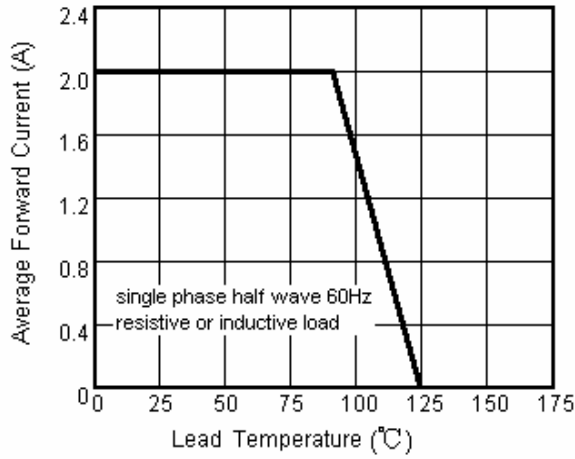


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

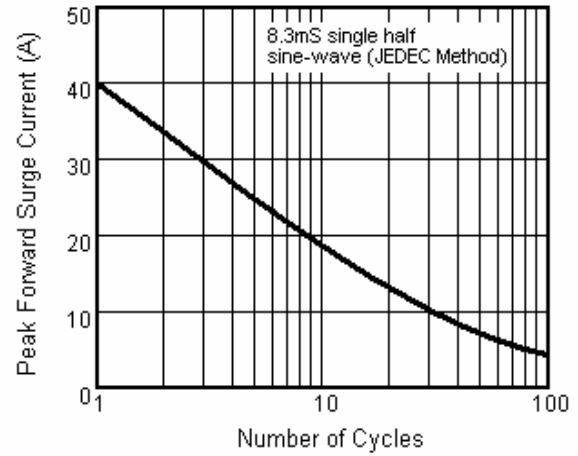


Fig.3 Typical Instantaneous Forward Characteristics

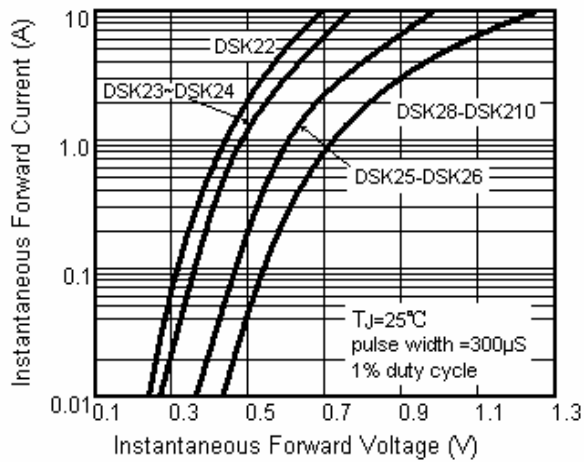


Fig.4 Typical Reverse Characteristics

